

SEMICONDUCTOR





TO220 package

KM series



High power dissipation, extruded heatsinks designed to accommodate one or more TO220 packages via a clip retaining feature (clips available separately). Shaped to minimise board space, with a threaded slot provided to aid assembly. Choice of thermal resistance.

	Th. Res.	Length (L)	Manf. Part No & Order Code
	3.3°C/W	100mm	KM100-1
	Device retaining clip (with legs) Device retaining clip (without legs for space saving)		4426 4525